

Notice of References Cited	Application/Control No. 09/901,837	Applicant(s)/Patent Under Reexamination BATRA ET AL.	
	Examiner Caridad M. Everhart	Art Unit 2825	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	C.-C. Lee, et al. "roles of Ti-intermetallic compound layers on the electromigration resistance of Al-Cu interconnecting stripes" J. Appl. Phys. vol. 71, No. 12,(15 June 1992), pp. 5877-5887).
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